



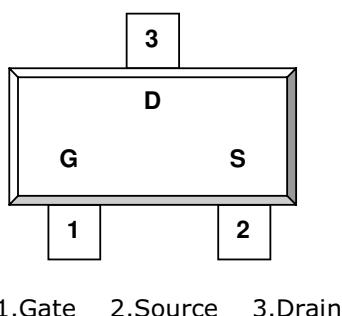
DESCRIPTION

The G2342SRG is the N-Channel logic enhancement mode power field effect transistor is produced using high cell density, DMOS trench technology.

This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management and other batter powered circuits, and low in-line power loss are needed in a very small outline surface mount package.

PIN CONFIGURATION

SOT-23

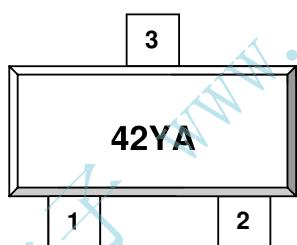


FEATURE

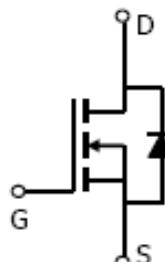
- 20V/6.0A, $R_{DS(ON)} = 35m\Omega$ (Typ.)
@ $V_{GS} = 10V$
- 20V/5.0A, $R_{DS(ON)} = 48m\Omega$
@ $V_{GS} = 4.5V$
- 20V/4.5A, $R_{DS(ON)} = 90m\Omega$
@ $V_{GS} = 2.5V$
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and Maximum DC current capability
- SOT-23 package design

PART MARKING

SOT-23



Y: Year Code A: Process Code



ORDERING INFORMATION

Part Number	Package	Part Marking
G2342SRG	SOT-23	42YA

* Process Code : A ~ Z ; a ~ z

* G2342SRG ; S : SOT23 R : TapeReel; G:Pb-Free

GTM

6.0A N Channel Enhancement Mode MOSFET

G2342SRG**ABSOULTE MAXIMUM RATINGS (Ta = 25°C Unless otherwise noted)**

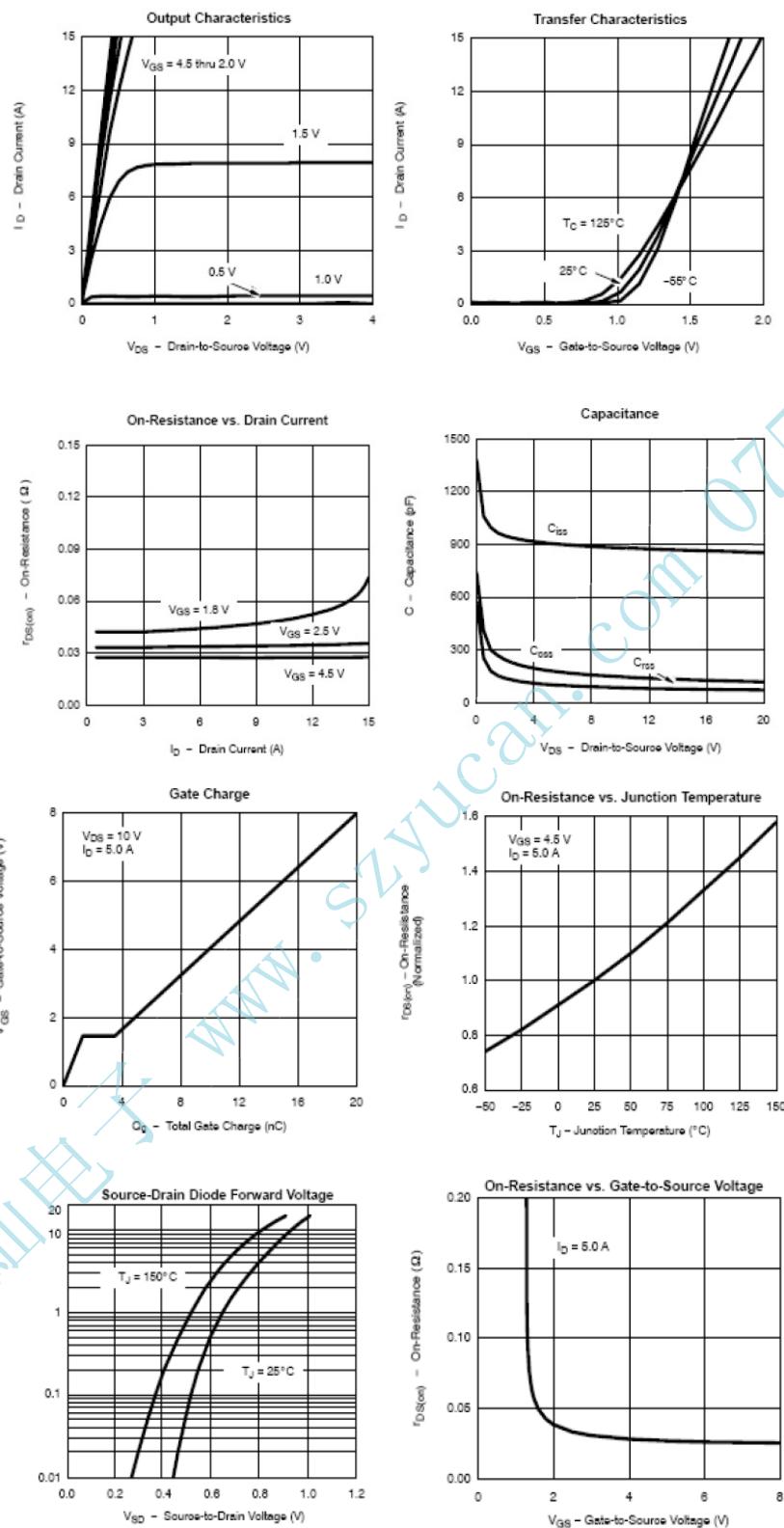
Parameter	Symbol	Typical	Unit
Drain-Source Voltage	V _{DSS}	20	V
Gate-Source Voltage	V _{GSS}	±12	V
Continuous Drain Current (T _J =150°C)	T _A =25°C T _A =70°C	I _D 6.0 3.0	A
Pulsed Drain Current	I _{DM}	10	A
Continuous Source Current (Diode Conduction)	I _S	1.0	A
Power Dissipation	T _A =25°C T _A =70°C	P _D 1.25 0.8	W
Operation Junction Temperature	T _J	150	°C
Storage Temperature Range	T _{STG}	-55/150	°C
Thermal Resistance-Junction to Ambient	R _{θJA}	140	°C/W


ELECTRICAL CHARACTERISTICS (Ta = 25°C Unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit	
Static							
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =250μA	20			V	
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	0.4		1.2	V	
Gate Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V			±100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =20V, V _{GS} =0V			1	uA	
		V _{DS} =20V, V _{GS} =0V T _J =85°C			10		
Drain-source On-Resistance	R _{D(on)}	V _{GS} =10V, I _D =6.0A		0.035		Ω	
		V _{GS} =4.5V, I _D =5.0A		0.048			
		V _{GS} =2.5V, I _D =4.5A		0.090			
Forward Transconductance	g _f	V _{DS} =15V, I _D =5.0A		30		S	
Diode Forward Voltage	V _{SD}	I _S =1.7A, V _{GS} =0V		0.9	1.2	V	
Dynamic							
Total Gate Charge	Q _g	V _{DS} =10V V _{GS} =4.5V I _D ≡5A		10	13	nC	
Gate-Source Charge	Q _{gs}			1.4			
Gate-Drain Charge	Q _{gd}			2.1			
Input Capacitance	C _{iss}	V _{DS} =10V V _{GS} =0V F=1MHz		600		pF	
Output Capacitance	C _{oss}			120			
Reverse Transfer Capacitance	C _{rss}			100			
Turn-On Time	t _{d(on)} tr	V _{DD} =10V R _L =10Ω I _D =1A V _{GEN} =4.5V R _G =6Ω		15	25	nS	
				40	60		
Turn-Off Time	t _{d(off)} tf			45	65		
				30	40		

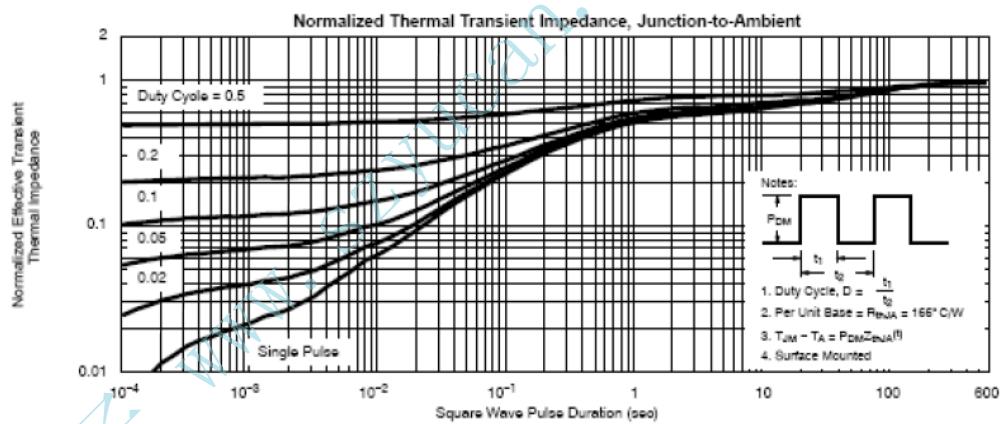
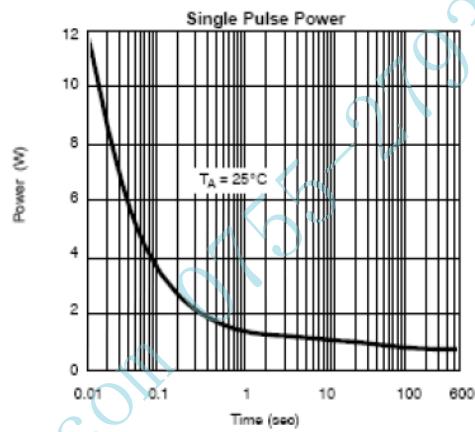
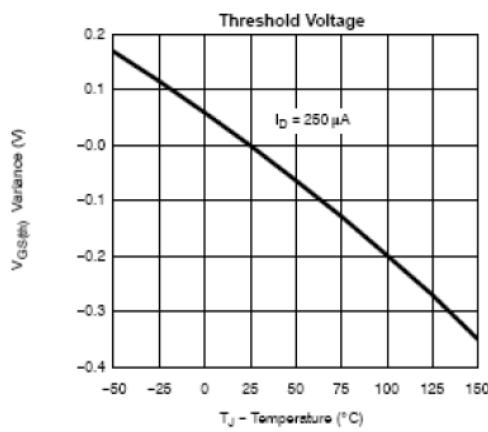


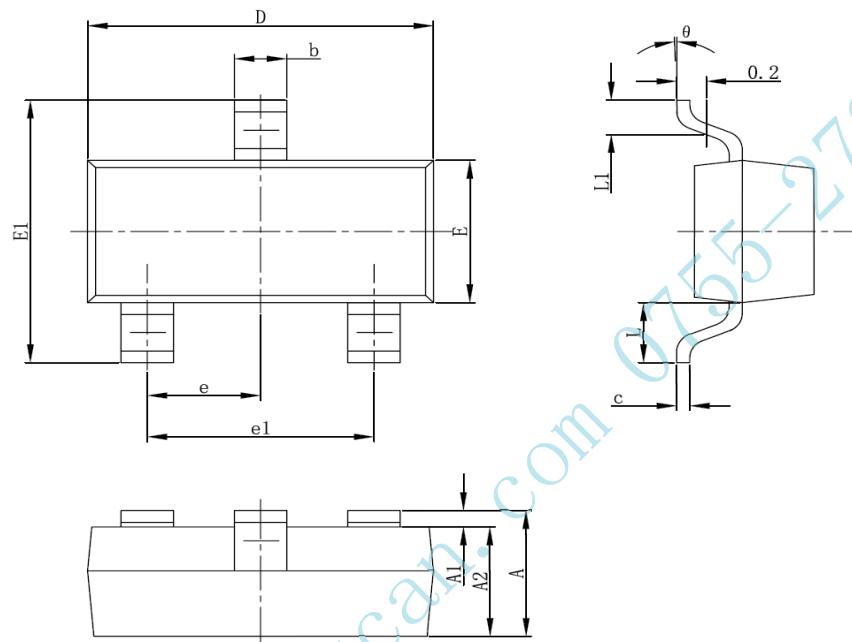
TYPICAL CHARACTERISTICS (25°C Unless noted)





TYPICAL CHARACTERISTIC



**SOT-23 PACKAGE OUTLINE**

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950TYP		0.037TYP	
e1	1.800	2.000	0.071	0.079
L	0.550REF		0.022REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°